Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**.019”**



**.019”**

**Top Material: Al**

**Backside Material: Au**

**Bond Pad Size: Base = 3.5 X 4.3 Emitter = 3.5 X 4.5**

**Backside Potential: Collector**

**Mask Ref: CP591**

**APPROVED BY: MG DIE SIZE: .019” X .019” DATE: 2/9/23**

**MFG: CENTRAL SEMI THICKNESS: .009” P/N:2N2907A**